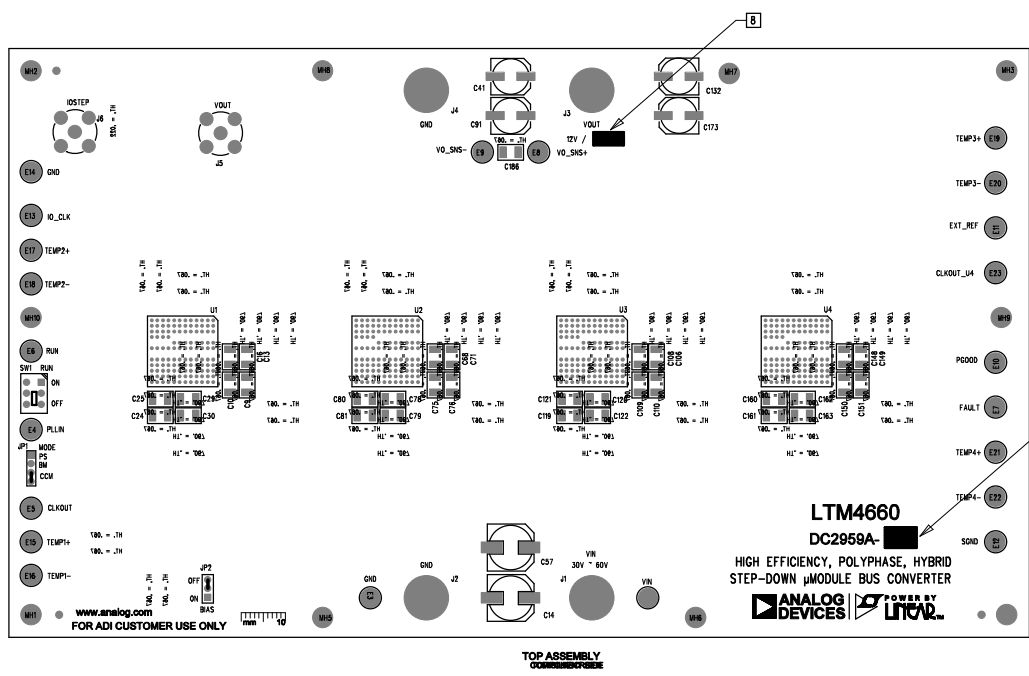
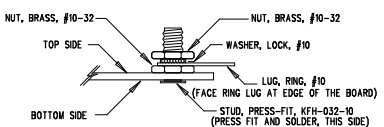




REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	2	PRODUCTION	HZ 06-01-22



- NOTES: UNLESS OTHERWISE SPECIFIED
1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
 2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
 3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
 4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
 5. DEPANALIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
 6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
 7. INSTALL 4 STANDOFFS AS SHOWN BELOW:
TOP SIDE
BOTTOM SIDE
PCB
4X STANDOFF, NYLON, SNAP ON.
- 8 SEE THE BILL OF MATERIALS TO MARK THE APPROPRIATE ASSEMBLY TYPE WITH BLACK PERMANENT MARKER.



APPROVALS		 		www.linear.com	
PCB DES.	AN	FOR ADI CUSTOMER USE ONLY			
APP ENG.	HZ	TITLE: TOP ASSEMBLY DRAWING HIGH EFFICIENCY, POLYPHASE, HYBRID STEP-DOWN μ MODULE BUS CONVERTER			
		SIZE	IC NO. LTM4660I	REV.	2
		N/A	DC2959A(A,B,C)		
SCALE = NONE		FILENAME: DC2959A-2.PCB		SHT 1 OF 2	